## Opening the Box and Running the Packet Error Rate Test

### 1. Kit Contents

2 x CC2650 Evaluation Modules  
Documentation

Note! The CC2650EMK is an add-on kit for the CC2650DK. It is assumed that you already have two SmartRF06EB boards. The SmartRF06EB can be purchased separately on TI eStore.

The RF boards in this kit are designed, but not certified, to comply with FCC, IC and ETSI requirements.

### 2. SmartRF06EB Overview

![SmartRF06EB Overview Diagram](image)

#### Insert the EM into the 06EB

Insert a CC2650 board into the SmartRF06EB as shown above.

**Caution!** The kit contains ESD sensitive components. Handle with care to prevent permanent damage.

### 3. Power Options

The CC2650EM should be powered through the SmartRF06EB, which will supply a voltage from 2.1 V to 3.6 V to the daughter card. The SmartRF06EB can be powered in several different ways:

- **USB (5 V through USB plug)**
- **2 x 1.5V AAA alkaline batteries (non rechrg.)**
- **External regulated power supply**

**External Regulated Power Supply Requirements:**

- **Nominal voltage:** 2.1 to 3.3 VDC
- **Maximum voltage:** 3.6 VDC
- **Max Current:** 1000 mA
- **Efficiency Level V**

**Warning!** To minimize risk of injury or property damage, never use rechargeable batteries to power the board. Do not leave the EVM powered when unattended.

### 4. Select Power Source

The power source is selected using the Source switch on the left hand side of the SmartRF06EB.

- **In “USB” position,** the EM is powered over USB, running at **3.3V.**
- **In “BAT” position,** the board is powered from batteries or an external source, running at **2.1V.**

The 2.1V regulator can be bypassed by shorting the pins on the "regulator bypass" jumper. In this case, the EM is powered directly from the external source or batteries.

**Note!** There should only be one active power source at any one time.

### 5. Welcome Screen

Turn on power with the Main Power switch. You should now see the Texas Instruments logo and a short description of the buttons on the LCD. Pushing any of the five buttons on the board will take you to the main menu.

**Note!** The packet error rate test only runs on the 7x7 variant of the CC2650EM.

**Note!** If you don’t see anything on the screen (when you have the 7x7 board) make sure the board is correctly powered (see step 4 and 5 above).

### 6. Select Board and Protocol

Start by selecting the plug-in board you have.

Then select the protocol.

**In this guide, we will use BLE, but the settings and operations that follow will be the same or similar for IEEE 802.15.4.**

### 7. Select Channel and Mode

Once you have selected the protocol, you should select which frequency you want to operate at. For BLE you can choose any of the three advertising channels or the data channels.

Then select the type of test you want to run. Packet mode is the Packet Error Rate test. CW is a continuous wave signal, either modulated or unmodulated.

---

1 When using an external power supply, make sure it meets the listed requirements in addition to complying with applicable regional product regulatory and safety certification requirements such as UL, CSA, VDE, CCC, and PSE.
9. Select Direction

For the packet error rate test, set one of the boards up as the receiver (RX) and the other as the transmitter (TX). The receiver does not require any further set-up and is now ready to receive packets.

10. Select Burst Size and Rate

Next, still on the transmitter side, select the desired burst size, that is, the number of packets to transmit.

Then select the packet rate (number of packets to transmit per second).

11. Select Output Power

On the transmitter, select the desired output power.

12. Start Sending Packets

The transmitter is now configured and in idle state. Sending packets is started and stopped by pressing the Select button.

13. PER Test Results

On the receiver, the statistics window will show the error rate based on the number of lost or erroneous packets divided by the total number of packets that should have been received.

14. Next Steps

Please refer to your local TI FAE or contact person to get more information about the SimpleLink CC2650 device and other devices in this new family of ultra-low power wireless microcontrollers.

In particular, you will be able to start working with software development on the BLE Stack and other software solutions from TI.

We sincerely hope that you will enjoy working with the CC2650 device.

15. Troubleshooting

If you are experiencing problems with this test, please check the following:

- Nothing is shown in the display! Make sure the board is powered correctly (see steps 5 and 6 above).
- Please visit the kit web page and check for updated SW and documentation. Updated SW can be downloaded to the device using IAR Embedded Workbench for ARM or SmartRF Flash Programmer.

SmartRF™ Studio

1. Getting Started

SmartRF can be used to test the radio interface on the CC2650 via an XDS debugger from TI. The SmartRF06EB has an onboard XDS100v3 debugger and can serve this purpose.

Get an early adopter version of SmartRF Studio from your local TI FAE or contact person.

Before connecting SmartRF06EB to your PC, download and install SmartRF Studio from www.ti.com/smartrfstudio.

2. Launch SmartRF Studio

After installing the tool, connect the EB to the PC using the USB cable and start SmartRF Studio. Select the “2.4 GHz” tab and click the refresh (“Find device”) button in the lower right corner. Studio will now find the connected SmartRF06EB. Double click on the detected SmartRF06EB to launch the CC2650 device control panel.

3. Test the Radio

You can now configure the radio, run performance tests and run link tests with another CC2650 device controlled either by your own software or by SmartRF Studio.

Web sites: www.ti.com/wirelessconnectivity E2E Forum: e2e.ti.com/support/wireless_connectivity

Make sure to subscribe to the Low-Power RF Newsletter to receive information about updates to documentation, new product releases, and more. Sign up on the TI web pages.
IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms. No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use. Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have not been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

- Audio
  - www.ti.com/audio
- Amplifiers
  - amplifier.ti.com
- Data Converters
  - dataconverter.ti.com
- DLP® Products
  - www.dlp.com
- DSP
  - dsp.ti.com
- Clocks and Timers
  - www.ti.com/clocks
- Interface
  - interface.ti.com
- Logic
  - logic.ti.com
- Power Mgmt
  - power.ti.com
- Microcontrollers
  - microcontroller.ti.com
- RFID
  - www.ti-rfid.com
- OMAP Applications Processors
  - www.ti.com/omap
- Wireless Connectivity
  - www.ti.com/wirelessconnectivity

Applications

- Automotive and Transportation
  - www.ti.com/automotive
- Communications and Telecom
  - www.ti.com/communications
- Computers and Peripherals
  - www.ti.com/computers
- Consumer Electronics
  - www.ti.com/consumer-apps
- Energy and Lighting
  - www.ti.com/energy
- Industrial
  - www.ti.com/industrial
- Medical
  - www.ti.com/medical
- Security
  - www.ti.com/security
- Space, Avionics and Defense
  - www.ti.com/space-avionics-defense
- Video and Imaging
  - www.ti.com/video
- e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2015, Texas Instruments Incorporated